Product/Process Change Notice - PCN 12_0253 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: AD8202 Minor Die Revision and Datasheet Change

Publication Date: 05-Nov-2012

Effectivity Date: 03-Feb-2013 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

1. Increasing polyimide overcoat thickness from 7um to 19um for the wafer fabrication process of the AD8202.

2. Reallocate the use of existing pads on Met1 for use as Kelvin pads which will be connected to the input pins (pins 1 and 8).

3. Remove Min/Max limits rated at 25C (system gain, common mode & voltage offset) from specification table on page 3 and replace with Min/Max limits over the entire temperature range.

Reason For Change

1. Additional polyimide thickness reduces die sensitivity to package stress.

2. Reallocating the use of existing pads on Met1 for use as Kelvin pads will allow the trim process to give increased accuracy of offset voltage, common mode, and gain.

3. Updating the datasheet to specify Min/Max limits over the entire temperature range reflects the current ADI practice for specifying products used by automotive customers.

Impact of the change (positive or negative) on fit, form, function & reliability

The additional polyimide thickness and kelvin pads applied to the AD8202 will not affect the fit, form or function of the device. The performance of the part will continue to match the specifications in the datasheet.
Data sheet changes will have no effect on production flow or test limits.

Summary of Supporting Information

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Report Summary.

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_12_0253_Rev_-_AD8202_Rev J_QP 9943_summary.doc

Attachment 2: Type: Revised Datasheet Specification

ADI_PCN_12_0253_Rev_-_AD8202_Preliminary_Rev_G.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (13)				
AD8202 / AD45091	AD8202 / AD45098	AD8202 / AD8202WYRMZ	AD8202 / AD8202WYRMZ-RL	AD8202 / AD8202WYRZ
AD8202 / AD8202WYRZ-RL	AD8202 / AD8202YRMZ	AD8202 / AD8202YRMZ-R7	AD8202 / AD8202YRMZ-RL	AD8202 / AD8202YRZ
AD8202 / AD8202YRZ-R7	AD8202 / AD8202YRZ-RL	AD8202 / ADW66000YRZ		

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	05-Nov-2012	03-Feb-2013	Initial Release